

# GSTMMBT3904AF

## NPN General Purpose Transistor

### Product Description

Collector-Emitter Voltage 40V  
Collector Current 200mA

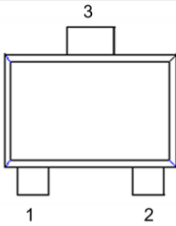
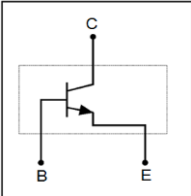
### Features

- Complementary to GSTMMBT3906AF
- RoHS Compliant and Halogen Free

### Mechanical Data

- Case : SOT-723 Package

### Package and Pin Assignment

SOT-723		Equivalent Circuit
		
Pin	Description	
1	BASE	
2	EMITTER	
3	COLLECTOR	

### Ordering and Marking Information

Ordering Information			
Part Number	Package	Marking Code	Quantity/Reel
GSTMMBT3904AF	SOT-723	1N	8,000 PCS
GSTMMBT3904 1 2			
- Product Code: GSTMMBT3904	- Package Code: 1 is A for SOT-723 Package	- Green Level: 2 is F for RoHS Compliant and Halogen Free	
Marking Information			
1N			
- Product Code: 1N			

GSTMMBT3904AF

## Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise specified)

Symbol	Parameter	Rating	Unit
V <sub>CEO</sub>	Collector-Emitter Voltage	40	V
V <sub>CBO</sub>	Collector-Base Voltage	60	V
V <sub>EBO</sub>	Emitter-Base Voltage	6.0	V
I <sub>C(DC)</sub>	Collector Current (DC)	200	mA
P <sub>D</sub>	Power Dissipation T <sub>A</sub> =25°C*	100	mW
R <sub>ΘJA</sub>	Thermal Resistance, Junction to Ambient	1250	°C/W
T <sub>J</sub>	Junction Temperature Range	150	°C
T <sub>STG</sub>	Storage Temperature Range	-55 to +150	°C

\* Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

## Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>(BR)CEO</sub>	Collector-Emitter Breakdown Voltage	I <sub>C</sub> =1.0mA, I <sub>B</sub> =0mA	40	-	V
V <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	I <sub>C</sub> =10uA, I <sub>E</sub> =0mA	60	-	V
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	I <sub>E</sub> =10uA, I <sub>C</sub> =0mA	6.0	-	V
I <sub>CBO</sub>	Collector-Base Cutoff Current	V <sub>CB</sub> =30V, I <sub>E</sub> =0	-	100	nA
I <sub>CEX</sub>	Collector-Emitter Cutoff Current	V <sub>CE</sub> =30V, V <sub>EB(OFF)</sub> =3V	-	50	nA
I <sub>EBO</sub>	Emitter-Base Cutoff Current	V <sub>EB</sub> =5V, I <sub>C</sub> =0mA	-	100	nA
h <sub>FE</sub>	DC Current Gain	I <sub>C</sub> =10mA, V <sub>CE</sub> =1.0V	100	300	-
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	I <sub>C</sub> =50mA, I <sub>B</sub> =5.0mA		0.3	V
V <sub>BE(sat)</sub>	Base-Emitter Saturation Voltage	I <sub>C</sub> =50mA, I <sub>B</sub> =5.0mA		0.95	V
f <sub>T</sub>	Current Gain Bandwidth Product	I <sub>C</sub> =10mA, V <sub>CE</sub> =20V, f=100MHz	300	-	MHz
t <sub>d</sub>	Delay Time	V <sub>CC</sub> =3.0V, I <sub>C</sub> =10mA, I <sub>B1</sub> =1.0mA	-	35	ns
t <sub>r</sub>	Rise Time		-	35	ns
t <sub>s</sub>	Storage Time	V <sub>CC</sub> =3.0V, I <sub>C</sub> =10mA, I <sub>B1</sub> =I <sub>B2</sub> =1.0mA	-	200	ns
t <sub>f</sub>	Fall Time		-	50	ns

## Typical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise specified)

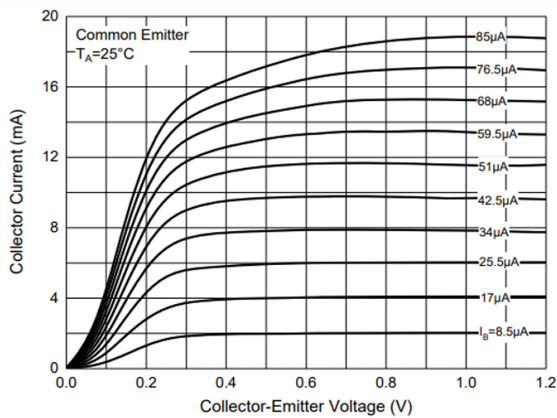


Figure 1. Static Characteristic

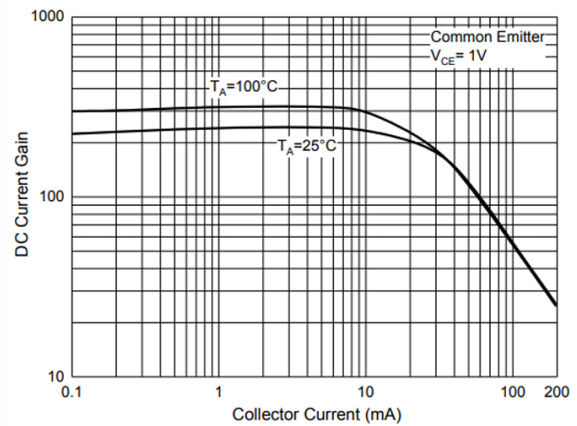


Figure 2. DC Current Gain Characteristics

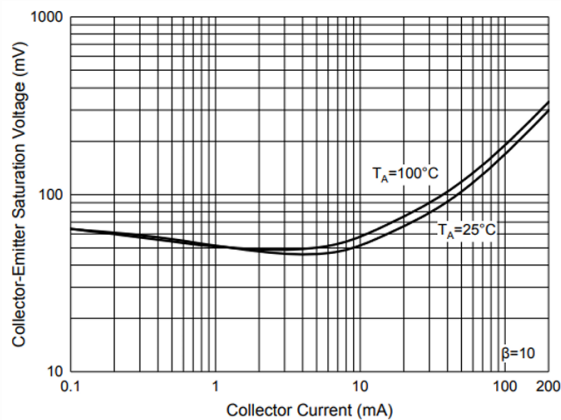


Figure 3. Collector-Emitter Saturation Voltage

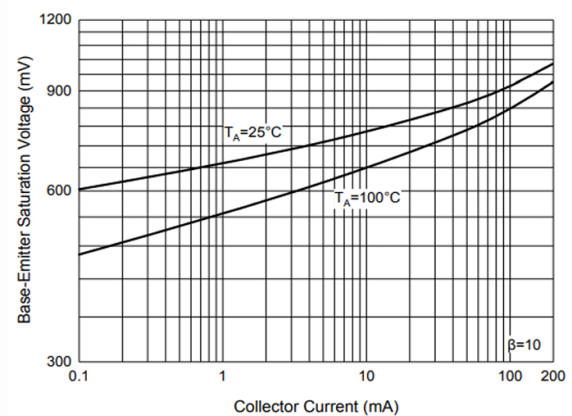


Figure 4. Base-Emitter Saturation Voltage

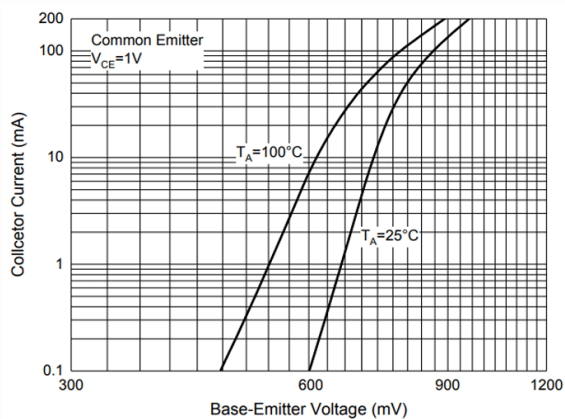


Figure 5. Base-Emitter Voltage Characteristics

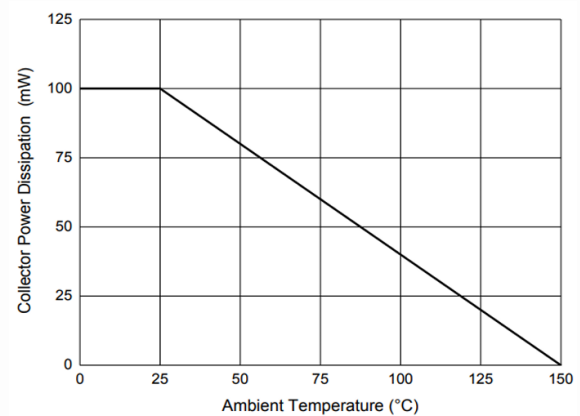
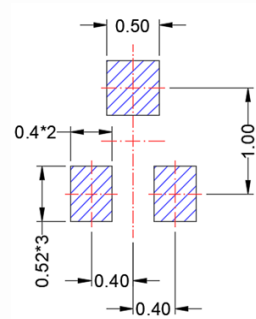
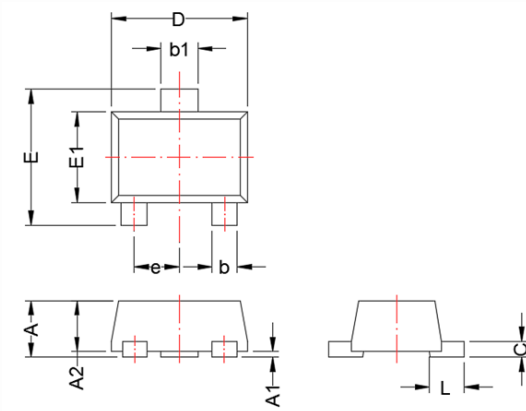


Figure 6. Power Derating Curve

# SOT-723

## Package Dimension

## Recommended Land Pattern



(Unit: mm)

Dimensions				
SYMBOL	Millimeters		Inches	
	MIN	MAX	MIN	MAX
A	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
A2	0.45	0.55	0.018	0.022
b	0.15	0.30	0.006	0.012
b1	0.25	0.40	0.010	0.016
c	0.08	0.20	0.003	0.008
D	1.10	1.30	0.043	0.051
E	1.10	1.30	0.043	0.051
E1	0.70	0.90	0.028	0.035
e	0.4 BSC		0.016 BSC	
L	0.2	0.42	0.008	0.017





### NOTE:



Dimensions are exclusive of Burrs, Mold Flash and Tie Bar extrusions.

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